

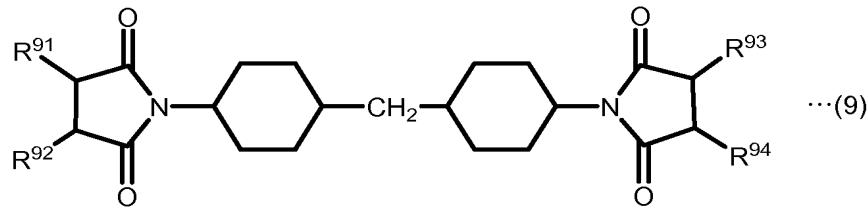
AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

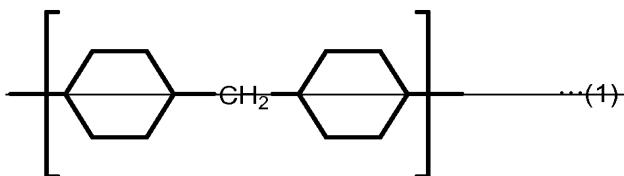
1. (Currently amended) A prepreg obtained by impregnating a resin composition comprising a resin with an imide structure and a thermosetting resin into a fiber base material with a thickness of 5-50 µm, wherein said resin with an imide structure is a polyamideimide resin having the structure represented by the following general formula (9):

[Chemical Formula 9]



[wherein R⁹¹, R⁹², R⁹³ and R⁹⁴ each represent a carbon atom from a portion of the cyclic or linear structure composing the polyamideimide resin], and said resin has a structure that includes a structure represented by the following general formula (1):

[Chemical Formula 1]



2. (Original) A prepreg according to claim 1, wherein said resin with an imide structure has a siloxane structure.

3. – 8. (Cancelled).

9. (Previously presented) A prepreg according to claim 1, wherein said thermosetting resin is an epoxy resin.

10. (Previously presented) A prepreg according to claim 1, wherein said thermosetting resin is an epoxy resin with two or more glycidyl groups.

11. (Previously presented) A prepreg according to claim 1, wherein said resin composition further contains a phosphorus-containing compound, and said resin composition contains said thermosetting resin at 1-140 parts by weight with respect to 100 parts by weight of said resin with an imide structure, and phosphorus at 0.1-5 wt% of the total weight of the resin solid portion.

12. (Previously presented) A prepreg according to claim 1, wherein said resin composition further contains a hindered phenol-based or organic sulfur compound-based antioxidant.

13. (Original) A prepreg according to claim 12, wherein said antioxidant is one or more types of antioxidant selected from the group consisting of butylated hydroxyanisole, 2,6-di-t-butyl-4-ethylphenol, 2,2'-methylene-bis(4-methyl-6-t-butylphenol), 4,4'-thiobis-(3-methyl-6-t-butylphenol), 4,4'-butyldenebis(3-methyl-6-t-butylphenol), 1,1,3-tris(2-methyl-4-hydroxy-5-t-butylphenyl)butane, 1,3,5-trimethyl-2,4,6-tris(3,5-di-t-butyl-4-hydroxybenzyl)benzene, tetrakis-[methylene-3-(3',5'-di-t-

butyl-4'-hydroxyphenylpropionate)methane, dilauryl thioldipropionate and distearyl thioldipropionate.

14. (Previously presented) A prepreg according to claim 1, which has a combustion distance of no greater than 100 mm in a UL-94 VTM test, when cured to form a base material.

15. (Previously presented) A metal foil-clad laminate obtained by stacking a prescribed number of prepgs according to claim 1, situating a metal foil on either or both sides thereof and subjecting the stack to heat and pressure.

16. (Original) A printed circuit board obtained by forming a circuit on the metal foil of a metal foil-clad laminate according to claim 15.

17. (Previously presented) A prepreg according to claim 1, wherein said polyamideimide resin contains at least 70 mol% of a polyamideimide molecule having at least 10 amide groups in the molecule.

18. (Previously presented) A prepreg according to claim 1, wherein said film base material is a glass cloth with a thickness of 5-50 μm .